NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE3025Q uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =30V,I_D =25A

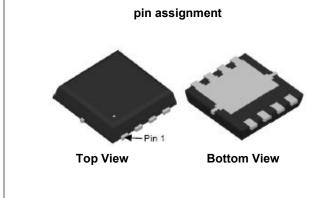
 $R_{DS(ON)} < 10 m\Omega @ V_{GS} = 10 V$

 $R_{DS(ON)}$ < 14m Ω @ V_{GS} =4.5V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- SMPS and general purpose applications
- Hard switched and high frequency circuits
- Uninterruptible power supply



(2) D

Schematic diagram

7 D

6 D

100% UIS TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3025Q	NCE3025Q	DFN3.3X3.3-8L	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous	I _D	25	Α	
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	17	А	
Pulsed Drain Current	I _{DM}	50	А	
Maximum Power Dissipation	P _D	25	W	
Derating factor		0.2	W/℃	
Single pulse avalanche energy (Note 5)	E _{AS}	70	mJ	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$	

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R _{eJC}	5	°C/W
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Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

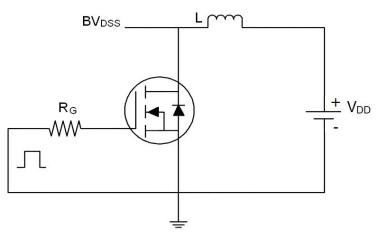
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	1	1.6	3	V
Drain-Source On-State Resistance		V _{GS} =10V, I _D =10A	-	7.0	10	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	10.5	14	
Forward Transconductance	G FS	V _{DS} =5V,I _D =20A	15	-	-	S
Dynamic Characteristics (Note4)	•					
Input Capacitance	Clss	\/ 45\/\/ O\/	_	1530	-	PF
Output Capacitance	Coss	V _{DS} =15V,V _{GS} =0V,	-	250	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	198	-	PF
Switching Characteristics (Note 4)	•					
Turn-on Delay Time	t _{d(on)}		-	10	-	nS
Turn-on Rise Time	t _r	V _{DD} =15V,I _D =10A	-	8	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{GEN} =1.8 Ω	-	30	-	nS
Turn-Off Fall Time	t _f		-	5	-	nS
Total Gate Charge	Qg	1/ 451/1 04	-	32.3	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =9A,	-	4.9	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	6.9	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-	0.85	1.2	V
Diode Forward Current (Note 2)	Is		-	-	25	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 10A	-	22	35	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs(Note3)	-	12	20	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

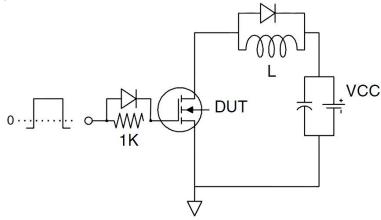
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}\text{C}$,VDD=15V,VG=10V,L=0.5mH,Rg=25 Ω

Test Circuit

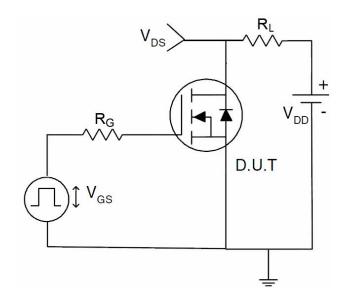
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

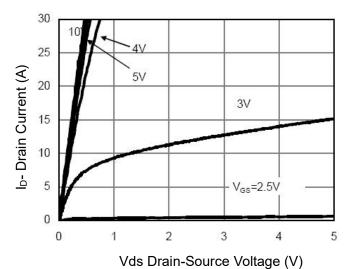


Figure 1 Output Characteristics

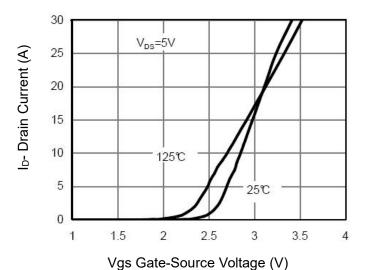


Figure 2 Transfer Characteristics

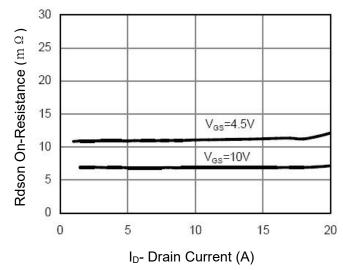


Figure 3 Rdson- Drain Current

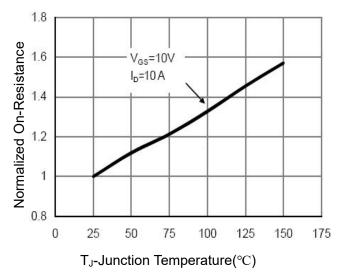


Figure 4 Rdson-Junction Temperature

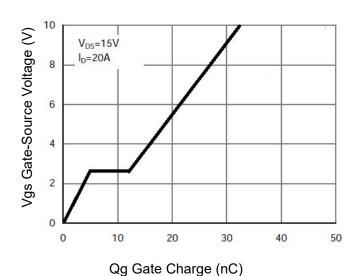


Figure 5 Gate Charge

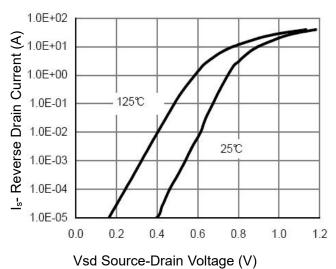


Figure 6 Source- Drain Diode Forward



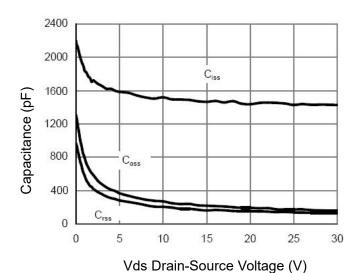


Figure 7 Capacitance vs Vds

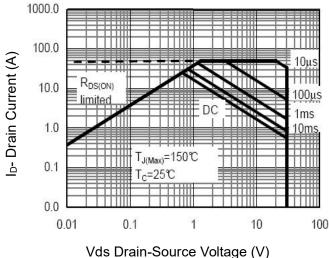
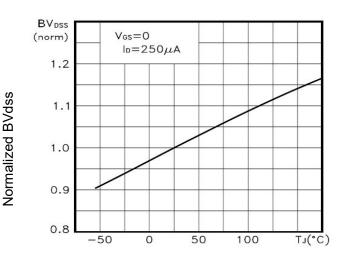
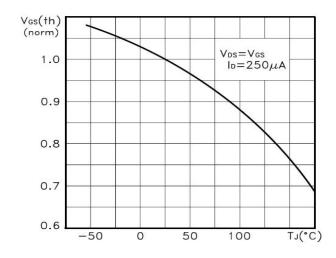


Figure 8 Safe Operation Area



T_J-Junction Temperature(°C)

Figure 9 BV_{DSS} vs Junction Temperature



 $\label{eq:TJ-Junction} $$T_{J}$-Junction Temperature(^{\circ}C)$$ Figure 10 $V_{GS(th)}$ vs Junction Temperature$

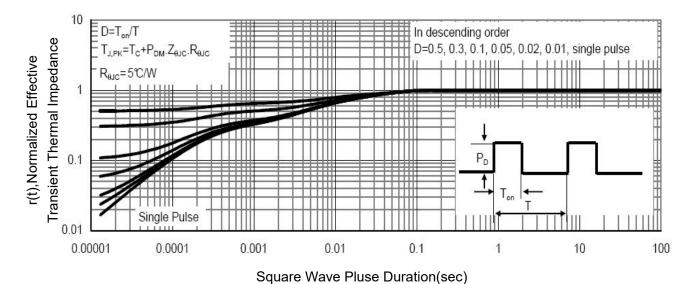
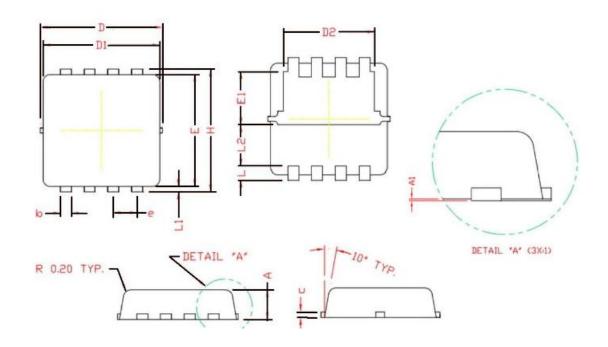


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN3.3X3.3-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
A	0.70	0.80	0.90	
A1	0.00	0.03	0.05	
b	0.24	0.30	0.35	
С	0.10	0.15	0.20	
D	3. 25	3. 32	3.40	
D1	3.05	3. 15	3. 25	
D2	2.40	2.50	2.60	
E	3.00	3.10	3.20	
E1	1.35	1.45	1.55	
е	0.65 BSC.			
Н	3.20	3.30	3.40	
L	0.30	0.40	0.50	
L1	0.10	0.15	0.20	
L2	1. 13 REF.			

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